

In The Claims:

Claims 1-8 (canceled)

9. (original) A chip suitable for detecting edge defects thereof by electrically testing, comprising:

an active surface;
a plurality of bump electrodes centrally arranged in two rows on the active surface;
two test bumps located at each end of the two rows of the bump electrodes; and
a test circuit around the edge of the chip on the active surface, wherein ends of the test circuit are electrically connected to the test bumps, respectively, and two of the leads are connected to the two test bumps, respectively.

10. (original) The tape carrier package of claim 9, wherein the material of the test circuit includes polysilicon and metal.

Claims 11-12 (canceled)